

Specification for Approval

Date: 2024/1/1

Customer:

BYTEK P/N: BCM1210F-SERIES

CUSTOMER P/N:

DESCRIPTION:

QUANTITY: pcs

REMARK:		
Customer Approval Feedback		

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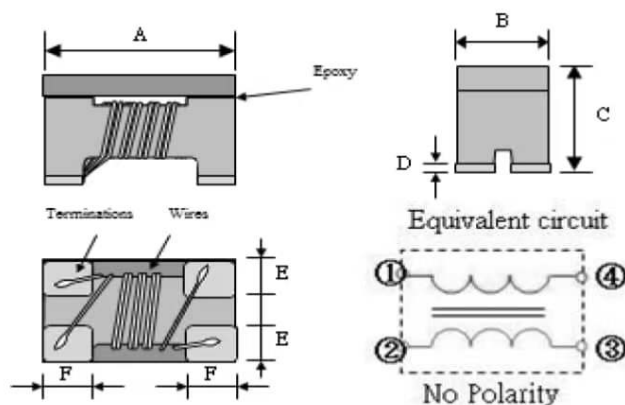
Wire Wound Power Common Mode Filter

BCM1210F-SERIES

1. Features

- Operating temperature -40~+125℃ (Including self - temperature rise)

2. Dimension



Unit:mm

Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)
BCM1210	1.2±0.2	1.0±0.2	0.9 max.	0.15 max.	0.36 Typ	0.33 Typ

3. Part Numbering

BCM 1210 F - 900 - 03

A B C D E

A: Series

B: Dimension BxC

C: Type

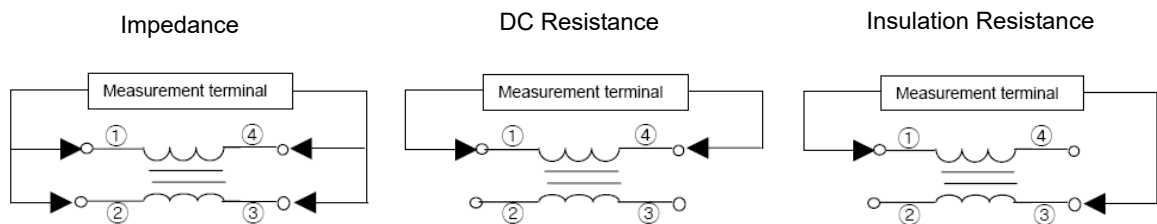
D: Impedance 900=90Ω

E: Materials

4. Specification

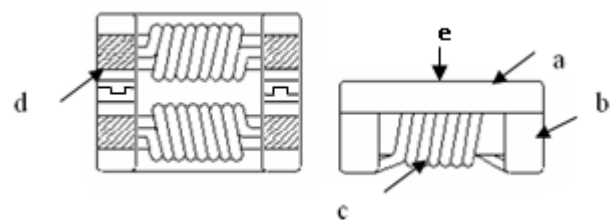
Part Number	Impedance (Ω ±25%)	Test Frequency (MHz)	DC Resistance (Ω) max.	Rated Current (A) max.	Rated Volt. (Vdc) max.	Insulation Resistance (MΩ) min.
BCM1210F-670-03	67	100	0.4	300	50	10
BCM1210F-900-03	90	100	0.5	280	50	10
BCM1210F-121-03	120	100	0.55	270	50	10
BCM1210F-161-03	160	100	0.58	260	50	10
BCM1210F-181-03	180	100	0.6	260	50	10
BCM1210F-251-03	250	100	0.7	230	50	10
BCM1210F-331-03	330	100	0.8	200	50	10

5. Schematic Diagram



6. Materia

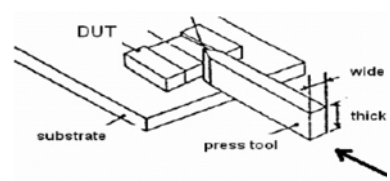
No.	Description	Specification
a.	Upper Plate	Ceramics Core (Black)
b.	Core	Ferrite Core
c.	Wire	Enameled Copper
d.	Termination	Ag/Ni/Sn + Sn Solder
e.	Mark	Laser Marking



7. Reliability and Test Condition

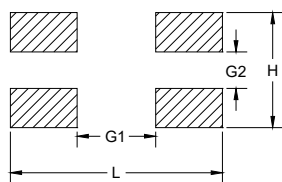
Item	Performance	Test Condition
Operating temperature	-40~+125°C (Including self - temperature rise)	
Storage temperature	-40~+125°C (on board)	
Electrical Performance Test		
Z(common mode)	Refer to standard electrical characteristics list.	Agilent-4291A+ Agilent -16197A
DCR		Agilent-4338B
I.R.		Agilent4339
Temperature Rise Test	Rated Current $\geq 1A$ ΔT 40°C Max	1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer

Reliability Test		
Life Test	<p>Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value</p>	<p>Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature : 125±2℃ Applied current : rated current Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs</p>
Load Humidity		<p>Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Humidity : 85±2% R.H, Temperature : 85℃±2℃ Duration : 1000hrs Min. Bead : with 100% rated current , Inductance: with 10% rated current Measured at room temperature after placing for 24±2 hrs</p>
Moisture Resistance		<p>Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs,keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.</p>
Thermal shock		<p>Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Condition for 1 cycle Step1 : -40±2℃ 30±5min Step2 : 25±2℃ ≤0.5min Step3 : 125±2℃ 30±5min Number of cycles : 500 Measured at room temperature after placing for 24±2 hrs</p>
Vibration		<p>Oscillation Frequency: 10Hz~2KHz~10Hz for 20 minute Equipment : Vibration checker Total Amplitude:10g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations) *</p>

Item	Performance	Test Condition														
Bending	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.														
Shock		<table><tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr><tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr><tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr></table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec												
SMD	50	11	Half-sine	11.3												
Lead	50	11	Half-sine	11.3												
Solder ability	More than 95% of the terminal electrode should be covered with solder.	a. Method B, 4 hrs @155°C dry heat @235°C±5°C Testing Time :5 +0/-0.5 seconds b. Method D category 3. (8hours ± 15 min)@ 260°C±5°C Testing Time :30 +0/-0.5 seconds														
Resistance to Soldering Heat		Depth: completely cover the termination <table><tr><th>Temperature(°C)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr><tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr></table>	Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1						
Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles													
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1													
Terminal Strength	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. 														

8. Soldering and Mounting

8-1. Recommended PC Board Pattern



8-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-2.1 Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

8-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 350°C tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.

Fig.1 Soldering Reflow

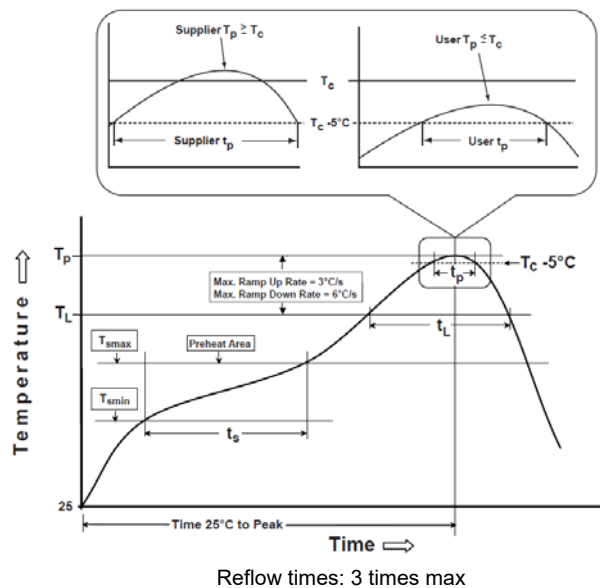


Fig.2 Iron Reflow

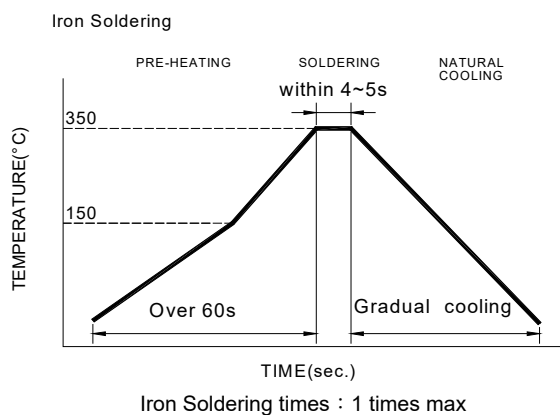


Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(t_s)from(T_{smin} to T_{smax})	150°C 200°C 60-120seconds
Ramp-up rate(T_L to T_p)	3°C/second max.
Liquidus temperature(T_L) Time(t_L)maintained above T_L	217°C 60-150 seconds
Classification temperature(T_c)	See Table (1.2)
Time(t_p) at $T_c - 5^\circ\text{C}$ (T_p should be equal to or less than T_c .)	< 30 seconds
Ramp-down rate(T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

T_p: maximum peak package body temperature, **T_c**: the classification temperature.

For user (customer) **T_p** should be equal to or less than **T_c**.

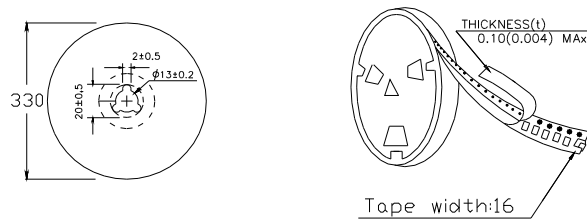
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

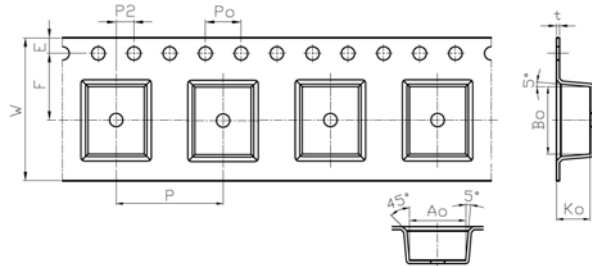
Reflow is referred to standard IPC/JEDEC J-STD-020E .

9. Packaging Information

9-1. Reel Dimension



9-2. Tape Dimension

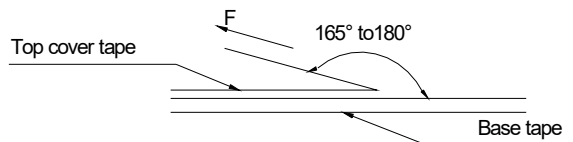


Series	W(mm)	Bo(mm)	Ao(mm)	Ko(mm)	P0(mm)	P2(mm)	F(mm)	E(mm)	P(mm)	t(mm)
BCM1210	16.00±0.3/-0.1	1.40±0.1	1.15±0.1	0.93±0.1	4.0±0.1	2.0±0.1	3.5±0.1	1.75±0.1	4.0±0.1	0.35±0.05

9-3. Packaging Quantity

Size	Reel
BCM1210	3000

9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions(component level)
 - To maintain the solderability of terminal electrodes:
 1. BYTEK products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
 3. Recommended products should be used within 12 months form the time of delivery.
 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1.Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2.The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3.Bulk handling should ensure that abrasion and mechanical shock are minimized.